

SEMITRANS[®] 2

SPT IGBT Module

SKM 100GB128D

Features

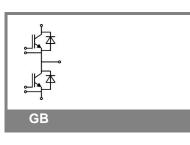
- SPT = Soft-Punch-Through technology
- V_{CEsat} with positive temperature coefficient
- High short circuit capability, self limiting to 6 x l_c

Typical Applications

- AC inverter drives
- UPS
- Electronic welders at f_{sw} up to 20 kHz

Absolute Maximum Ratings T _c = 25 °C, unless otherwise sp					
Symbol	Conditions		Values		
IGBT					
V _{CES}	T _j = 25 °C		1200	V	
I _C	T _j = 150 °C	T _c = 25 °C	145	Α	
		T _c = 80 °C	105	Α	
I _{CRM}	I _{CRM} =2xI _{Cnom}		150	А	
V _{GES}			±20	V	
t _{psc}	V_{CC} = 600 V; $V_{GE} \le 20$ V; VCES < 1200 V	T _j = 125 °C	10	μs	
Inverse Diode					
I _F	T _j = 150 °C	T _{case} = 25 °C	95	А	
		T _{case} = 80 °C	65	Α	
I _{FRM}	I _{FRM} =2xI _{Fnom}		150	А	
I _{FSM}	t _p = 10 ms; sin.	T _j = 150 °C	720	А	
Module					
I _{t(RMS)}			200	А	
T _{vj}			- 40 + 150	°C	
T _{stg}			- 40 + 125	°C	
V _{isol}	AC, 1 min.		4000	V	

Characteristics			$T_c = 25 \text{ °C}$, unless otherwise specified			
Symbol	Conditions		min.	typ.	max.	Units
IGBT	_					
V _{GE(th)}	$V_{GE} = V_{CE}, I_C = 3 \text{ mA}$		4,5	5,5	6,45	V
I _{CES}	V_{GE} = 0 V, V_{CE} = V_{CES}	T _j = 25 °C		0,1	0,3	mA
V _{CE0}		T _j = 25 °C		1	1,15	V
		T _j = 125 °C		0,9	1,05	V
r _{CE}	V _{GE} = 15 V	T _j = 25°C		13	16	mΩ
		T _j = 125°C		16	20	mΩ
V _{CE(sat)}	I _{Cnom} = 75 A, V _{GE} = 15 V			1,9	2,35	V
		T _j = 125°C _{chiplev.}		2,1	2,55	V
C _{ies}				6,2		nF
C _{oes}	V_{CE} = 25, V_{GE} = 0 V	f = 1 MHz		0,74		nF
C _{res}				0,71		nF
Q _G	V _{GE} = -8V - +20V			860		nC
R _{Gint}	T _j = 25 °C			5		Ω
t _{d(on)}				175		ns
t _r	R _{Gon} = 4,7 Ω	$V_{CC} = 600V$		38		ns
É _{on}	D = 47.0	I _C = 75A		9		mJ
t _{d(off)}	R_{Goff} = 4,7 Ω	T _j = 125 °C V _{GE} = ±15V		370 65		ns ns
t _f E _{off}		GE - 10V		7,5		mJ
R _{th(j-c)}	per IGBT			.,•	0,21	K/W





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Characteristics								
Symbol	Conditions		min.	typ.	max.	Units		
Inverse D	Inverse Diode							
$V_F = V_{EC}$	I _{Fnom} = 75 A; V _{GE} = 0 V			2	2,5	V		
		T_j = 125 °C _{chiplev} .		1,8		V		
V _{F0}		T _j = 25 °C		1,1	1,2	V		
r _F		T _j = 25 °C		12	17,3	mΩ		
I _{RRM}	I _F = 75 A	T _i = 125 °C		88		А		
Q _{rr}	di/dt = 2800 A/µs	,		13		μC		
E _{rr}	V_{GE} = -15 V; V_{CC} = 600 V			3,9		mJ		
$R_{th(j-c)D}$	per diode				0,5	K/W		
Module								
L _{CE}					30	nH		
R _{CC'+EE'}	res., terminal-chip	T _{case} = 25 °C		0,75		mΩ		
		T _{case} = 125 °C		1		mΩ		
R _{th(c-s)}	per module				0,05	K/W		
M _s	to heat sink M6		3		5	Nm		
M _t	to terminals M5		2,5		5	Nm		
w					160	g		

Features

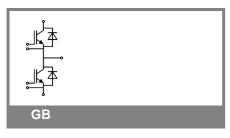
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This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

This technical information specifies semiconductor devices but promises no characteristics. No warranty or guarantee expressed or implied is made regarding delivery, performance or suitability.





Z _{th} Symbol	Conditions	Values	Units
Z _{th(j-c)} I R _i R _i R _i R _i tau _i tau _i	i = 1 i = 2 i = 3 i = 4 i = 1 i = 2	114 71 22 3 0,054 0,0115	mk/W mk/W mk/W s s
tau _i tau _i	i = 3 i = 4	0,0012 0,001	s s
Z R _i R _i R _i R _i tau _i tau _i tau _i tau _i	i = 1 i = 2 i = 3 i = 4 i = 1 i = 2 i = 3 i = 4	300 160 35,5 4,5 0,054 0,0071 0,0017 0,005	mk/W mk/W mk/W s s s s s

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